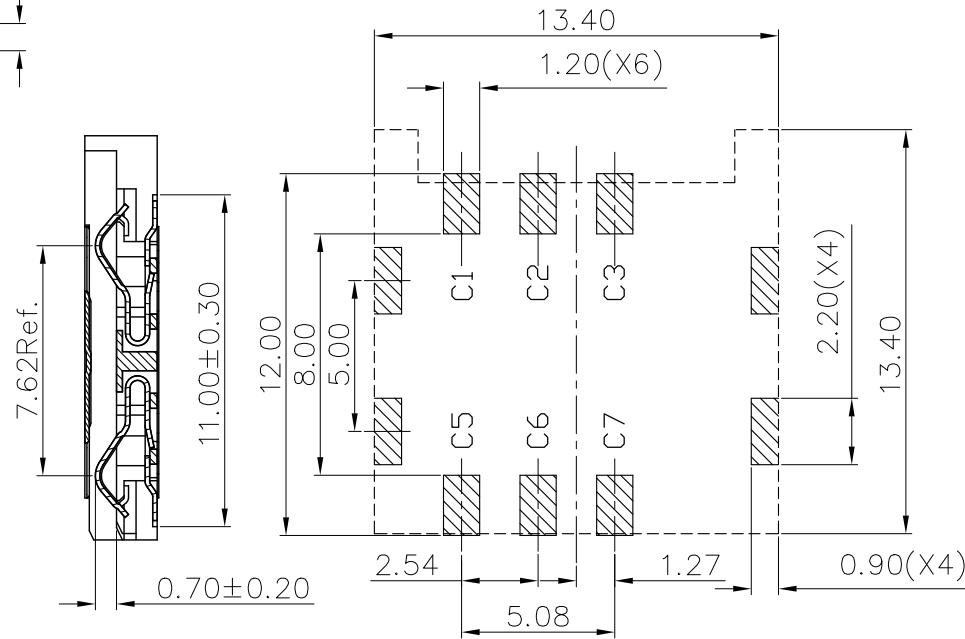
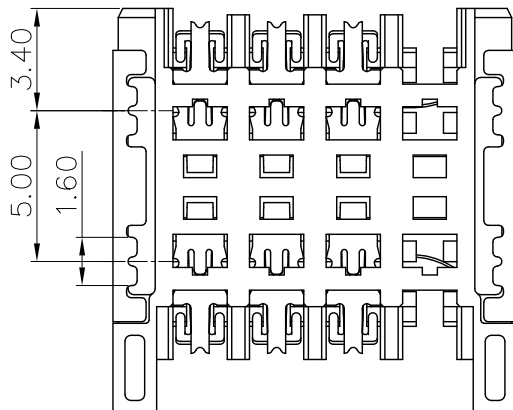
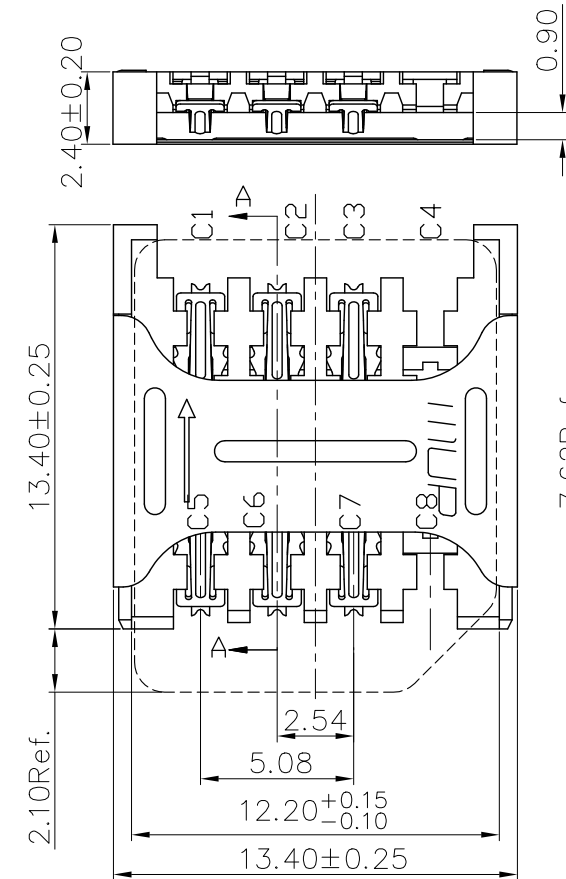
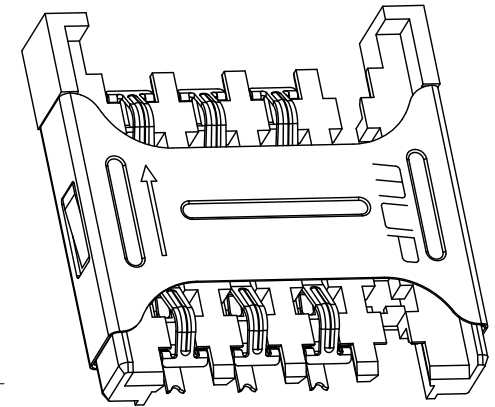


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1	NEW REVISION				Zoey Mar.04.2011
X2					



SECTION A-A

RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ± 0.05)



TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: $13.40 \times 13.40 \times 2.40$ mm

Weight: Approx 0.40 ± 0.1 g

Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: $50\text{m}\Omega$ typical, $100\text{m}\Omega$ max

Insulation resistance: $>1000\text{M}\Omega/500\text{V DC}$

3.Solderability

Vapor phase: 215°C , 30sec.Max

IR reflow: 250°C , 5sec.Max

Manual soldering: 370°C , 3sec.Max

4.Environmental Characteristics

Operating temperature: $-40^\circ\text{C} \sim +85^\circ\text{C}$

Operating humidity: $10\% \sim +95\% \text{RH}$

ITEM	PART NAME	Q'TY	MATERIAL	FINISH	
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0	
2	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated	
3	SHELL	1	Stainless steel	SMT area:Gold plated	
Unless otherwise specified, other tolerance are:			MUP[®] MUP INDUSTRIAL CO.,LTD.		
X	±0.35	X* ±5°	NAME: Micro-SIM Card Connector MODEL NO: MUP-C790-21 TYPE : H2.40 mm 6Pin		
X.X	±0.25	X.X* ±4°			
X.XX	±0.15	X.XX* ±3°			
X.XXX	±0.10	X.XXX* ±2°			
PROJ. 		UNIT MM	SCALE 1:1	DRAWN Zoey Mar.04.2011	
CUSTOMER DRAWING				DWG NO.: DWG-MUP-C790-21	
		CHECKED	Sean Mar.04.2011	SHEET 1/1	
		APPROVAL	Simon Mar.04.2011	REVISION X1	

